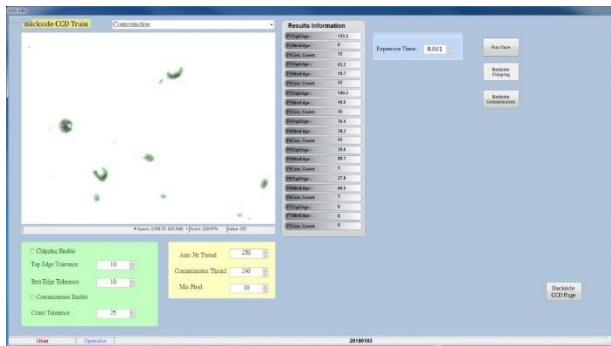


HDS-200

Die Sorting System

Features

- Support 8" /12" Frame wafer
- Output waffle tray 2" /3" /4" tray
- Output 6 bins maximum
- HDS-200 running cycle time $\leq 0.56s$
- HDS-200 UPH $\geq 6K$
- Tray P/N confirm
- Backside inspection (Option)
- P&P clean platform
- Easy change kit
- Dimension 1.5m(W) x 1.5m(L) x 2m(H)
- Clean room class 100 (HEPA)



Vision inspection:

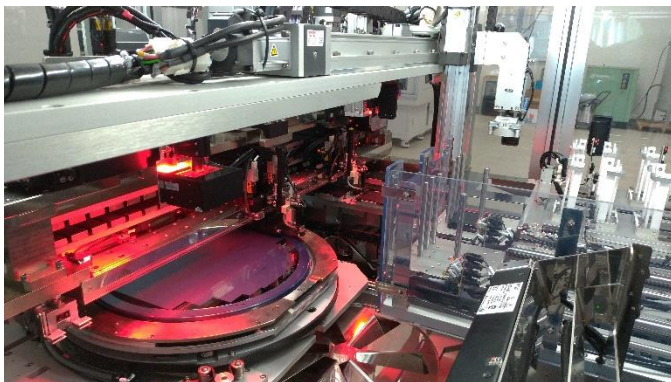
Surface and sawing lane

-- foreign material / chipping

-- scratch / crack

Resolution

-- 15 μ m / NG size ; 1 pixel = 3 μ m



Hypersonic

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Basic Functions

	Description
Basic functions	<ul style="list-style-type: none">• Wafer auto loading/unloading• Wafer tape expending(10 mm Maximum)• Mapping data confirm• Die transportation• 8" /12" wafer switch• Die backside inspection (Option)• Output tray In-pocket inspection• Output tray 2x3• Tray stack 2x3• Empty tray auto load• Ionizer• HEPA

Specification

Items	Spec.	Items	Spec.
UPH	6.0K ±10% (No backside inspection)	Wafer cassette	1
Cycle time	0.56 sec (maximum)	Empty tray	Stack height 150mm 4" , 20+ 2 sets
Wafer size	8" , 12"	Full tray	Stack height 100mm 4" , 15+ 6 sets
Waffle Tray size	2" , 3" , 4"	Tape type	Blue tape UV tape
Category/bins	6 (=2x3)	Vacuum cup	Auto height alignment
Die size range	1x1 ~ 35x18 mm		
Place accuracy	±40μm		
Backside resolution	15μm / NG size		
Vacuum cup change time	< 3 min		
Needle change time	< 5 min		